Erratum: Step instabilities in Fe/Cu(100) growth [Phys. Rev. Materials 1, 043403 (2017)]

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The artificially smoothened configuration shown in Fig. 5(d) of our paper was less than optimal and has now been replaced by a smoother configuration. Since the energy of the artificially smoothened configuration is still larger than that of the annealed configuration this does not change our conclusion that, while the Fe/Cu step-edge instability is driven by kinetics, energetics also plays a role.

FIG. 5. (a)–(c) Evolution of surface morphology shown in Figs. 3(a) and 3(b) after annealing at 250 K for times indicated. (d) Artificially smoothened configuration (see text). In (b) the energy barrier for the embedding of an Fe atom marked as “+” is 0.6 eV, followed by dislocation release with an energy barrier of 0.053 eV.